

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An ink jet printhead comprising:
a plurality of nozzles formed on a wafer substrate by lithographic etching and deposition techniques, each of the nozzles having a chamber for holding ejectable liquid, an ejection aperture in one wall of the chamber, and inlet for the ejectable liquid formed in a wall opposing that of the ejection aperture, a heater element suspended in the chamber for thermal contact with the ejectable liquid, the heater element having a planar structure configured parallel to that of the ejection aperture;
~~at least one heater element corresponding to each of the nozzles respectively, the heater element configured for thermal contact with a bubble forming liquid;~~
drive circuitry corresponding to each of the nozzles for controlling the operation of the heater element; such that,
heating the heater element to a temperature above the boiling point of the ~~bubble forming~~ejectable liquid forms a gas bubble that causes the ejection of a drop of an the ejectable liquid through the nozzle ejection aperture corresponding to that heater element; wherein,
~~the center of the drive circuitry is~~ formed in an area of the wafer substrate, the area having a centre point that is offset from the a center point of the corresponding nozzle ejection aperture by less than 200 microns.
2. (Currently Amended) The printhead of claim 1 wherein the center point of the drive circuitry is offset from the center point of the corresponding ejection aperture ~~nozzle~~-by less than 100 microns
3. (Currently Amended) The printhead of claim 1 wherein the center point of the drive circuitry is offset from the center point of the corresponding ejection aperture ~~nozzle~~-by less than 50 microns
4. (Currently Amended) The printhead of claim 1 wherein the center point of the drive circuitry is offset from the center point of the corresponding ejection aperture ~~nozzle~~-by less than 30 microns.
5. (Cancelled)
6. (Original) The printhead of claim 1 being configured to print on a page and to be a page-width printhead.
7. (Original) The printhead of claim 1 wherein each heater element is in the form of a cantilever beam.

8. (Currently Amended) The printhead of claim 1 wherein each heater element is configured such that an actuation energy of less than 500 nanojoules (nJ) is required to be applied to that heater element to heat that heater element sufficiently to form a said bubble in the ~~bubble-forming~~ ejectable liquid thereby to cause the ejection of a said drop.

9. (Original) The printhead of claim 1 configured to receive a supply of the ejectable liquid at an ambient temperature, wherein each heater element is configured such that the energy required to be applied thereto to heat said part to cause the ejection of a said drop is less than the energy required to heat a volume of said ejectable liquid equal to the volume of the said drop, from a temperature equal to said ambient temperature to said boiling point.

10. (Original) The printhead of claim 1 comprising a substrate having a substrate surface, wherein the areal density of the nozzles relative to the substrate surface exceeds 10,000 nozzles per square cm of substrate surface.

11. (Original) The printhead of claim 1 wherein each heater element has two opposite sides and is configured such that a said gas bubble formed by that heater element is formed at both of said sides of that heater element.

12. (Original) The printhead of claim 1 wherein the bubble which each element is configured to form is collapsible and has a point of collapse, and wherein each heater element is configured such that the point of collapse of a bubble formed thereby is spaced from that heater element.

13. (Original) The printhead of claim 1 comprising a structure that is formed by chemical vapor deposition (CVD), the nozzles being incorporated on the structure.

14. (Original) The printhead of claim 1 comprising a structure which is less than 10 microns thick, the nozzles being incorporated on the structure.

15. (Currently Amended) The printhead of claim 1 ~~comprising a plurality of nozzle chambers each corresponding to a respective nozzle, and wherein each nozzle has a plurality of said heater elements being suspended disposed within each the chamber, the heater elements within each chamber being formed on different respective layers to one another.~~

16. (Currently Amended) The printhead of claim 1 wherein ~~each the~~ heater element is formed of solid material more than 90% of which, by atomic proportion, is constituted by at least one periodic element having an atomic number below 50.

17. (Currently Amended) The printhead of claim 1 wherein ~~each the~~ heater element includes solid material and is configured for a mass of less than 10 nanograms of the solid material of that heater element to be heated to a temperature above said boiling point thereby to heat said part of the ~~bubble-forming~~ ejectable liquid to a temperature above said boiling point to cause the ejection of a said drop.

18. (Currently Amended) The printhead of claim 1 wherein ~~each~~ the heater element is substantially covered by a conformal protective coating, the coating of ~~each heater element~~ having been applied substantially to all sides of the heater element simultaneously such that the coating is seamless.

19. (Currently Amended) ~~A printer~~ A printer system which incorporates a printhead, the printhead comprising:

a plurality of nozzles, formed on a wafer substrate by lithographic etching and deposition techniques, each of the nozzles having a chamber for holding ejectable liquid, an ejection aperture in one wall of the chamber, and inlet for the ejectable liquid formed in a wall opposing that of the ejection aperture, a heater element suspended in the chamber for thermal contact with the ejectable liquid, the heater element having a planar structure configured parallel to that of the ejection aperture;

~~at least one heater element corresponding to each of the nozzles respectively, the heater element configured for thermal contact with a bubble forming liquid;~~

~~drive circuitry corresponding to each of the nozzles for controlling the operation of the heater element; such that,~~

~~heating the heater element to a temperature above the boiling point of the bubble ejectable forming liquid forms a gas bubble that causes the ejection of a drop of an the ejectable liquid through the ejection aperture nozzle corresponding to that heater element; wherein,~~

~~the center of the drive circuitry is formed in an area of the wafer substrate, the area having a centre point that is offset from the a center point of the corresponding ejection aperture nozzle by less than 200 microns.~~

20. (Currently Amended) The system of claim 19 wherein the center point of the drive circuitry is offset from the center point of the corresponding ejection aperture nozzle by less than 100 microns

21. (Currently Amended) The system of claim 19 wherein the center point of the drive circuitry is offset from the center point of the corresponding ejection aperture nozzle by less than 50 microns

22. (Currently Amended) The system of claim 19 wherein the center point of the drive circuitry is offset from the center point of the corresponding ejection aperture nozzle by less than 30 microns.

23. (Cancelled)

24. (Cancelled)

25. (Original) The system of claim 19 being configured to print on a page and to be a page-width printhead.

26. (Original) The system of claim 19 wherein each heater element is in the form of a cantilever beam.

27. (Currently Amended) The system of claim 19 wherein each heater element is configured such that an actuation energy of less than 500 nanojoules (nJ) is required to be applied to that heater element to heat that heater element sufficiently to form a said bubble in the ~~bubble-forming~~ ejectable liquid thereby to cause the ejection of a said drop.
28. (Original) The system of claim 19, wherein the printhead is configured to receive a supply of the ejectable liquid at an ambient temperature, and wherein each heater element is configured such that the energy required to be applied thereto to heat said part to cause the ejection of a said drop is less than the energy required to heat a volume of said ejectable liquid equal to the volume of the said drop, from a temperature equal to said ambient temperature to said boiling point.
29. (Currently Amended) The system of claim 19 ~~comprising a substrate having a substrate surface,~~ wherein the areal density of the nozzles relative to the substrate surface exceeds 10,000 nozzles per square cm of substrate surface.
30. (Original) The system of claim 19 wherein each heater element has two opposite sides and is configured such that a said gas bubble formed by that heater element is formed at both of said sides of that heater element.
31. (Original) The system of claim 19 wherein the bubble which each element is configured to form is collapsible and has a point of collapse, and wherein each heater element is configured such that the point of collapse of a bubble formed thereby is spaced from that heater element.
32. (Original) The system of claim 19 comprising a structure that is formed by chemical vapor deposition (CVD), the nozzles being incorporated on the structure.
33. (Original) The system of claim 19 comprising a structure which is less than 10 microns thick, the nozzles being incorporated on the structure.
34. (Currently Amended) The system of claim 19 ~~comprising a plurality of nozzle chambers each corresponding to a respective nozzle, and wherein~~ a plurality of said heater elements ~~being disposed~~ are suspended within each chamber, the heater elements ~~within each chamber~~ being formed on different respective layers to one another.
35. (Currently Amended) The system of claim 19 wherein ~~each~~ the heater element is formed of solid material more than 90% of which, by atomic proportion, is constituted by at least one periodic element having an atomic number below 50.
36. (Currently Amended) The system of claim 19 wherein ~~each~~ the heater element includes solid material and is configured for a mass of less than 10 nanograms of the solid material of that heater element to be heated to a temperature above said boiling point thereby to heat said part of the ~~bubble-forming~~ ejectable liquid to a temperature above said boiling point to cause the ejection of a said drop.

37. (Currently Amended) The system of claim 19 wherein ~~each the~~ heater element is substantially covered by a conformal protective coating, the coating ~~of each heater element~~ having been applied substantially to all sides of the heater element simultaneously such that the coating is seamless.

38. (Currently Amended) A method of ejecting drops of an ejectable liquid from a printhead, the printhead comprising a plurality of nozzles, formed on a wafer substrate by lithographic etching and deposition techniques, each of the nozzles having a chamber for holding ejectable liquid, an ejection aperture in one wall of the chamber, and inlet for the ejectable liquid formed in a wall opposing that of the ejection aperture, a heater element suspended in the chamber for thermal contact with the ejectable liquid, the heater element having a planar structure configured parallel to that of the ejection aperture;

~~at least one heater element corresponding to each of the nozzles respectively, the heater element configured for thermal contact with a bubble forming liquid;~~

drive circuitry corresponding to each of the nozzles for controlling the operation of the heater element; wherein,

~~the center of the drive circuitry is~~ formed in an area of the wafer substrate, the area having a centre point that is offset from the a center point of the corresponding nozzle by less than 200 microns;

the method comprising the steps of:

heating the heater element to a temperature above the boiling point of the ~~bubble forming~~ ejectable liquid to form a gas bubble that causes the ejection of a drop of ~~an the~~ ejectable liquid from the nozzle; and

supplying the nozzle with a replacement volume of the ejectable liquid equivalent to the ejected drop.

39. (Currently Amended) The method of claim 38 wherein the center point of the drive circuitry is offset from the center point of the corresponding nozzle by less than 100 microns

40. (Currently Amended) The method of claim 38 wherein the center point of the drive circuitry is offset from the center point of the corresponding nozzle by less than 50 microns

41. (Currently Amended) The method of claim 38 wherein the center point of the drive circuitry is offset from the center point of the corresponding nozzle by less than 30 microns.

42. (Cancelled)

43. (Original) The method of claim 38 wherein the printhead is configured to print on a page and to be a page-width printhead.

44. (Original) The method of claim 38 wherein said step of heating the at least one heater element is effected by applying an actuation energy of less than 500nJ to each such heater element.

45. (Original) The method of claim 38 wherein prior to the step of heating the at least one heater element, a supply of the ejectable liquid, at an ambient temperature, is fed to the printhead, wherein the step of heating is effected by applying heat energy to the at least one heater element, wherein said applied heat energy is less than the energy required to heat a volume of said ejectable liquid equal to the volume of said drop, from a temperature equal to said ambient temperature to said boiling point.

46. (Currently Amended) The method of claim 38 wherein ~~the printhead includes a substrate on which said nozzles are disposed,~~ the substrate having a substrate surface and the areal density of the nozzles relative to the substrate surface exceeding 10,000 nozzles per square cm of substrate surface.

47. (Original) The method of claim 38 wherein the at least one heater element has two opposing sides and the bubble is generated at both of said sides of each heated heater element

48. (Original) The method of claim 38 wherein the generated bubble is collapsible and has a point of collapse, and is generated such that the point of collapse is spaced from the at least one heater element.

49. (Original) The method of claim 38 wherein the printhead has a structure that is less than 10 microns thick and which incorporates said nozzles thereon.

50. (Original) The method of claim 38 wherein the nozzles of the printhead are formed by chemical vapor deposition (CVD).

51. (Currently Amended) The method of claim 38 wherein ~~the printhead has a plurality of nozzle chambers each chamber corresponding to a respective nozzle and a plurality of said heater elements are formed in each of the chambers, such that the heater elements in each chamber are formed on different respective layers to one another.~~

52. (Original) The method of claim 38 wherein the heater elements are formed of solid material more than 90% of which, by atomic proportion, is constituted by at least one periodic element having an atomic number below 50.

53. (Original) The method of claim 38 wherein the heater elements include solid material and wherein the step of heating at least one heater element comprises heating a mass of less than 10 nanograms of the solid material of each such heater element to a temperature above said boiling point.

54. (Original) The method of claim 38 wherein a conformal protective coating is applied to substantially to all sides of each of the heater elements simultaneously, such that the coating is seamless.